



Notice Date: 11.09.2007

Product Category: Linear Devices; Mixed Signal Devices; Supervisor;
PIC10xxx

Notification Subject: CCB#755: QUALIFICATION OF G600 TYPE MOLD
COMPOUNDS AND/OR Ag RING PLATED
LEADFRAME FOR SOT-23 PACKAGES AT VARIOUS
ASSEMBLY SITES

Notification Body:

Microchip Part#s Affected:

6L SOT-23 Using G600F Mold Compound at MMS (ATES) Assembly:

PIC10F200
PIC10F202
PIC10F204
PIC10F206
PIC10F220
PIC10F222
TC1035

5L SOT-23 Using G600 Mold Compound at UTL (NSEB) Assembly:

MCP6001R
MCP601R
MCP6021R
MCP6231R
MCP6241R
MCP6271R
MCP6281R
MCP6291R
MCP6541R
MCP6546M
MCP6546R
MCP6G41R
TC1034
TC1270A
TC1270AN
TC1271A

3L SOT-23 Using G600 Type V Mold Compound at MTAI Assembly:

MCP1700
MCP100
MCP103
MCP111
MCP112
TC1272A
TCM809
TCM810



3L SOT-23 Package Qualification Using G600 Type V Mold Compound and Ag Ring Plated Lead Frame at MTAI Assembly:

MCP1700
MCP100
MCP103
MCP111
MCP112
TC1272A
TCM809
TCM810

5L SOT-23 Using Ag Ring Plated Lead frame at MTAI Assembly:

MCP6001R
MCP601R
MCP6021R
MCP6231R
MCP6241R
MCP6271R
MCP6281R
MCP6291R
MCP6541R
MCP6546M
MCP6546R
MCP6G41R
TC1034
TC1270A
TC1270AN
TC1271A

Description of Change:
CHANGE IN BOM

Impacts to Data Sheet:
NONE

Reason for Change:
TO IMPROVE MANUFACTURABILITY

Estimated Change Implementation Date(s):
OCTOBER 31, 2007

Markings to Distinguish Revised From Unrevised Devices: (e.g.: Date Code, Device Marking, Ship Container Marking)
TRACEABILITY CODE